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**QUALCOMM LICENSES RADVISION SIP TOOLKIT TO POWER
BROADBAND MOBILE VIDEOTELEPHONY SOLUTIONS**

Fair Lawn, New Jersey, October 7, 2004 – RADVISION (Nasdaq: RVSN) today announced it has licensed its Session Initiation Protocol (SIP) developers toolkit to QUALCOMM Incorporated (Nasdaq: QCOM). Under this agreement, QUALCOMM is licensing RADVISION's award-winning SIP toolkit as the developer platform for QUALCOMM's Qvideophone™ videoconferencing solution, which is integrated into select QUALCOMM Mobile Station Modem™ (MSM™) chipsets and will initially target the CDMA2000® 1X-EV-DO-based mobile market.

The RADVISION SIP Developer Platform is a service creation platform that provides developers with an open, object-oriented architecture (coded in ANSI C) for building SIP-based communications products for the wireline, wireless, and mobile worlds. The platform features RADVISION's powerful standards-based SIP stack as well as multiple layers of APIs, from high-level APIs that hide the complexity of the protocol and enable rapid development of applications to mid and low level APIs that expose the intricacies of the protocol and allow for more detailed customization tuned to the specific requirements of the application or product. The RADVISION SIP Toolkit, a component of RADVISION's mobile/wireless developer suite of products, chosen by QUALCOMM, was specifically enhanced to meet the requirements of the mobile network including support of SigComp (Signaling Compression), mobile IP and multi homed host. The Toolkit also comes with SDP and RTP/RTCP libraries necessary for the development of advanced IP-based communications products.

“RADVISION is pleased that QUALCOMM has selected the powerful SIP Toolkit and Developer Suite to develop components of the QUALCOMM Qvideophone solution,” said Boaz Raviv, General Manager of RADVISION's Technology Business Unit. “RADVISION — with its strong track record in providing easy-to-use, feature-rich, and interoperable developer toolkits for IP protocol devices and applications — delivers time-to-market improvements while allowing developers to focus on creating advanced features and functionality.”

About RADVISION's Mobile/Wireless Developer Suite

The SIP Toolkit Developer Solution, part of RADVISION's award-winning Mobile/Wireless Developer suite, is specially enhanced to meet the requirements for mobile devices development. With these toolkits RADVISION provides its development partners with all the tools and complementary components necessary to effectively design and bring to market interoperable solutions for the 3G mobile network. RADVISION's suite of mobile developer solutions now supports all the main application protocols needed for the delivery of one-way, bidirectional, and multipoint data and multimedia content over a broadband mobile network including:

- SIP (Session Initiation Protocol) according to RFC3261
- SIP/SIMPLE (Presence and Instant Messaging)
- SIP/Sigcomp
- 3G-324M (for real-time conversational multimedia over 3G)
- RTSP (Real Time Streaming Protocol) Client Toolkit
- RTP/RTCP (Real Time Transport Protocol/Real Time Transport Control Protocol) that supports the special requirements of 3G and PoC (RFC 3550 & 3551- special enhancements in RTCP for PoC)

About RADVISION

RADVISION Ltd. (Nasdaq: RVSN) is the industry's leading provider of high quality, scalable and easy-to-use products and technologies for videoconferencing, video telephony, and the development of converged voice, video and data over IP and 3G networks. For more information please visit our website at www.radvision.com.

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